24 August 2026

dorsaVi Completes Foundational CMOS Fabrication for RRAM Validation Chip

Front-end-of-line and middle-of-line fabrication completed through TSMC's established CMOS process, enabling the validation wafers to advance into the program's proprietary RRAM integration phase.

Key Highlights:

- **CMOS fabrication completion marks key milestone.** Front-end-of-line (FEOL) transistor fabrication and middle-of-line (MOL) interconnects for the validation chip have been completed using TSMC's CMOS process, providing the silicon platform for subsequent RRAM integration.
- **Established CMOS foundation for proprietary RRAM integration.** Completing the underlying CMOS circuitry through TSMC's established process allows the Company's proprietary RRAM architecture to be subsequently integrated through dedicated back-end processing.
- **Wafers advance into proprietary RRAM integration.** The next stage begins with fabrication of the engineered via structure that forms the RRAM bottom electrode, followed by deposition of the proprietary RRAM material stack and subsequent BEOL processing toward electrical testing.
- **Advances high-value physical AI markets:** Progressing the validation chip into RRAM integration supports dorsaVi's roadmap toward low-power, non-volatile edge hardware for applications including robotics, exoskeletons, autonomous systems and other Physical AI platforms.

Melbourne, Australia – dorsaVi Limited (ASX: DVL) ("dorsaVi" or the "Company") is pleased to confirm that front-end-of-line (FEOL) transistor fabrication and middle-of-line (MOL) interconnects for its first RRAM-CMOS validation chip have been completed using TSMC's CMOS process. With the foundational CMOS platform now in place, the validation wafers can advance into dorsaVi's proprietary back-end-of-line (BEOL) RRAM integration sequence, beginning with fabrication of dedicated BEOL integration structures, followed by RRAM stack deposition, RRAM cell etching, and subsequent metal lines and interconnects. This milestone advances the Company's pathway toward an electrically testable RRAM-CMOS validation chip and its broader roadmap for low-power Physical AI hardware.

Critical Silicon Layer Complete

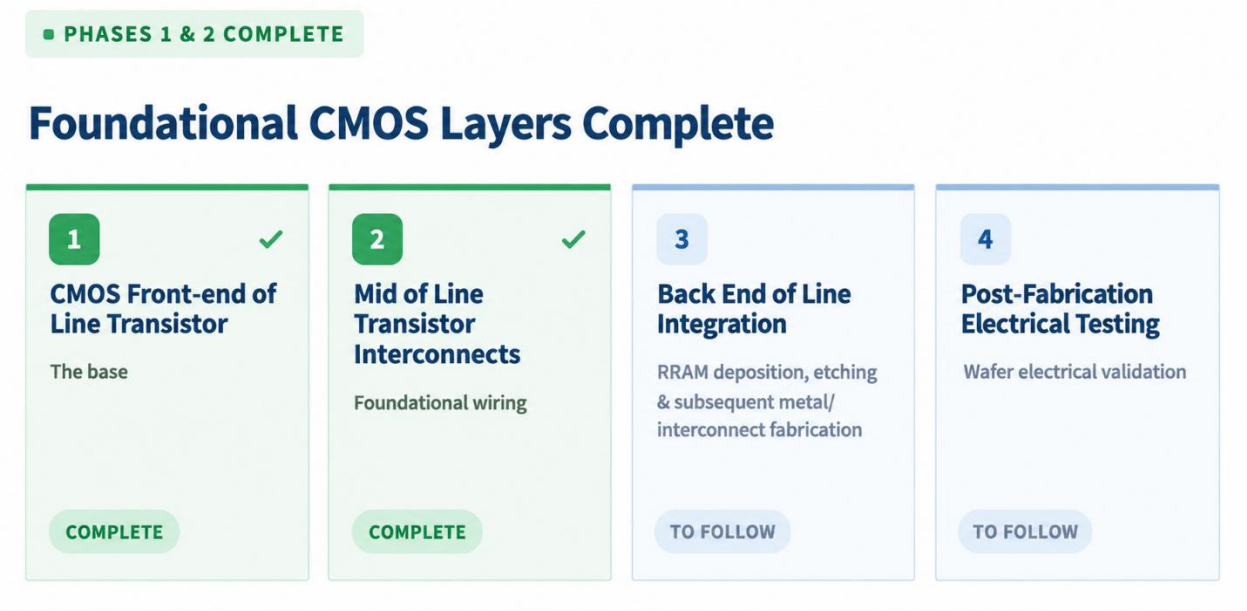

Figure 1: Showcasing process flow from the completed CMOS front-end and middle-of-line fabrication to the subsequent RRAM stack deposition and BEOL integration.

The front-end-of-line (FEOL) contains the transistor layer of the validation chip, while the middle-of-line (MOL) provides the local interconnects connecting these devices. Together, they form the foundational CMOS platform required for the Company's subsequent RRAM integration.

Fabricating these layers through TSMC's established CMOS process provides a proven foundation for the validation chip, allowing the next development phase to focus on the RRAM-specific integration steps within the back-end-of-line (BEOL).

This completes Phases 1 and 2 of the validation chip build. Work now advances into Phase 3, the BEOL RRAM integration sequence, encompassing dedicated integration structures, RRAM stack deposition, RRAM cell etching, and subsequent metal lines and interconnect fabrication.

Pushes forward high-value Physical AI markets

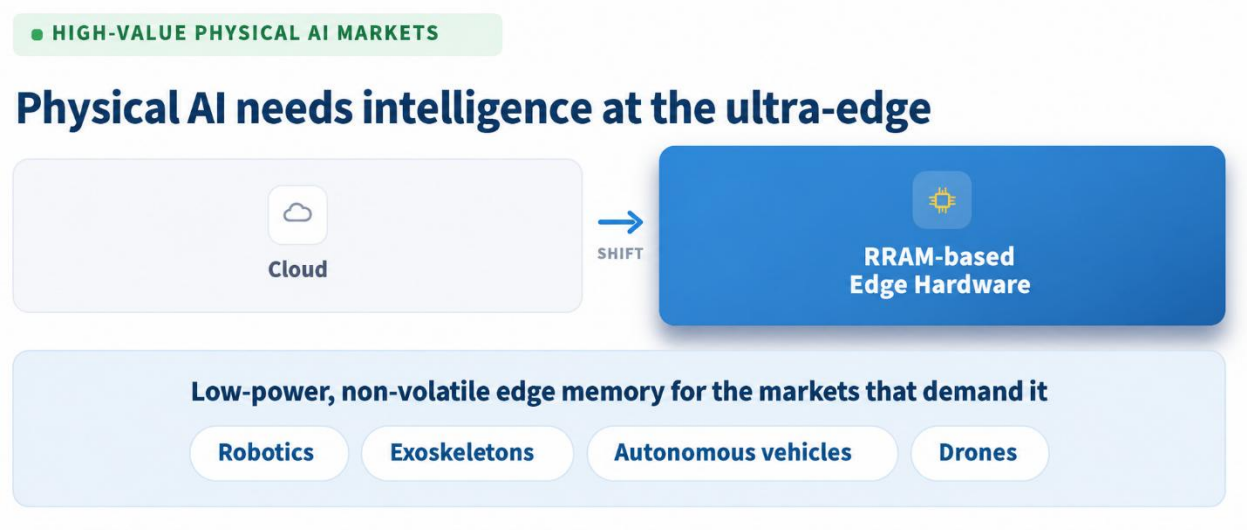

Figure 2: Infographic showing the shift from cloud processing to on-device edge intelligence, and the Physical AI markets targeted.

Physical AI systems including robotics, exoskeletons, autonomous vehicles and drones require processing and memory to sit at the edge, close to the sensor, rather than in the cloud. Power and memory efficiency are the binding constraints on what these systems can do locally.

The Company's RRAM technology is targeted directly at that constraint. Progress on the validation chip advances the roadmap toward memory that supports the local processing these markets increasingly demand.

CEO Commentary

Mathew Regan, Group Chief Executive Officer of dorsaVi, said:

> "We are very pleased with the progress of the dorsaVi–NTU RRAM development program, which continues to advance in line with our project plan.
>
> Completion of the CMOS front-end and middle-of-line fabrication is an important milestone, providing the physical foundation on which our proprietary RRAM technology can now be integrated.
>
> The program now moves into the RRAM-specific back-end integration phase, ahead of electrical validation. We look forward to reporting against the next defined milestones as the program progresses."

- ENDS -

This release has been authorised for lodgement to the ASX by the Board.

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Forward-Looking Statements

This announcement may contain certain forward-looking statements and projections. Such forward-looking statements/projections are estimates for discussion purposes only and should not be relied upon. Forward looking statements/projections are inherently uncertain and may therefore differ materially from results ultimately achieved. dorsaVi Limited does not make any representations and provides no warranties concerning the accuracy of the projections and disclaims any obligation to update or revise any forward-looking statements/projections based on new information, future events or otherwise, except to the extent required by applicable laws.

About dorsaVi

dorsaVi Ltd (ASX: DVL) is an ASX company focused on delivering intelligence at the ultra-edge. Enabling real time AI-driven decisions to be made locally, at the point of sensing, without reliance on cloud connectivity. dorsaVi's wearable sensor technology captures, quantifies, and assesses detailed human movement and position outside a biomechanics lab, in both real-time and real situations for up to 24 hours, across clinical applications, elite sports, and occupational health and safety. Underpinning this vision, dorsaVi is building the hardware foundations of the ultra-edge through strategic investments in neuromorphic computing and RRAM memory technology. dorsaVi's focus is on three major markets:

- Ultra-Edge Intelligence: dorsaVi's sensor platforms are designed to process and act on data locally, embedding AI-driven inference directly at the point of capture. By investing in neuromorphic computing and RRAM memory technology, dorsaVi enables real-time decision-making without round-tripping to the cloud, delivering lower latency, lower power consumption, and reliable operation in latency- and connectivity-constrained environments across industrial, clinical, and autonomous systems applications.

- Workplace: dorsaVi enables employers to assess risk of injury for employees as well as test the effectiveness of proposed changes to OHS workplace design, equipment or methods based on objective evidence. dorsaVi works either directly with major corporations, or through an insurance company's customer base with the aim of reducing workplace compensation and claims. dorsaVi has been used by major corporations including London Underground, Vinci Construction, Crown Resorts, Caterpillar (US), Boeing, Monash Health, Coles, Woolworths, Toll, Toyota, Orora, Mineral Resources and BHP.

- Clinical: dorsaVi is transforming the management of patients with its clinical solutions (ViMove+) which provide objective assessment, monitoring outside the clinic and immediate biofeedback. The clinical market is broken down into physical therapy (physiotherapists), hospital in the home and elite sports. Hospital in the home refers to the remote management of patients by clinicians outside of physical therapy (i.e. for orthopaedic conditions). Elite sports refer to the management and optimisation of athletes through objective evidence for decisions on return to play, measurement of biomechanics and immediate biofeedback to enable peak performance.

Further information is available at www.dorsavi.com